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Global 3D IC and 2.5D IC Market 2024 by Company, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global 3D IC and 2.5D IC market size was valued at USD million in 2023 and is forecast to a readjusted size of USD million by 2030 with a CAGR of % during review period.

In microelectronics, a three-dimensional integrated circuit (3D IC) is an integrated circuit manufactured by stacking silicon wafers or dies and interconnecting them vertically using, for instance, through-silicon vias (TSVs) or Cu-Cu connections, so that they behave as a single device to achieve performance improvements at reduced power and smaller footprint than conventional two dimensional processes.While a 2.5-dimensional integrated circuit (2.5D IC) is a package with an active electronic components (for example, a die or a chip) stacked on an interposer through conductive bumps or TSVs.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US$142.1 billion, up 17.0% year-on-year, sales in Europe were US$53.8 billion, up 12.6% year-on-year, and sales in Japan were US$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US$336.2 billion, down 2.0% year-on-year.

The Global Info Research report includes an overview of the development of the 3D IC

and 2.5D IC industry chain, the market status of Consumer Electronics (3D Wafer-level Chip-scale Packaging, 3D TSV), Telecommunication (3D Wafer-level Chip-scale Packaging, 3D TSV), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of 3D IC and 2.5D IC.

Regionally, the report analyzes the 3D IC and 2.5D IC markets in key regions. North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads the global 3D IC and 2.5D IC market, with robust domestic demand, supportive policies, and a strong manufacturing base.

Key Features:

The report presents comprehensive understanding of the 3D IC and 2.5D IC market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the 3D IC and 2.5D IC industry.

The report involves analyzing the market at a macro level:

Market Sizing and Segmentation: Report collect data on the overall market size, including the revenue generated, and market share of different by Type (e.g., 3D Wafer-level Chip-scale Packaging, 3D TSV).

Industry Analysis: Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the 3D IC and 2.5D IC market.

Regional Analysis: The report involves examining the 3D IC and 2.5D IC market at a regional or national level. Report analyses regional factors such as government incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

Market Projections: Report covers the gathered data and analysis to make future projections and forecasts for the 3D IC and 2.5D IC market. This may include estimating market growth rates, predicting market demand, and identifying emerging trends.

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The report also involves a more granular approach to 3D IC and 2.5D IC:

Company Analysis: Report covers individual 3D IC and 2.5D IC players, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios, partnerships, and strategies.

Consumer Analysis: Report covers data on consumer behaviour, preferences, and attitudes towards 3D IC and 2.5D IC This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Consumer Electronics, Telecommunication).

Technology Analysis: Report covers specific technologies relevant to 3D IC and 2.5D IC. It assesses the current state, advancements, and potential future developments in 3D IC and 2.5D IC areas.

Competitive Landscape: By analyzing individual companies, suppliers, and consumers, the report present insights into the competitive landscape of the 3D IC and 2.5D IC market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

Market Validation: The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

Market Segmentation

3D IC and 2.5D IC market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of value.

Market segment by Type

3D Wafer-level Chip-scale Packaging

3D TSV

2.5D

Market segment by Application

Consumer Electronics

Telecommunication

Industry Sector

Automotive

Military and Aerospace

Smart Technologies

Medical Devices

Market segment by players, this report covers

TSMC(Taiwan)

Samsung(South Korea)

Toshiba(Japan)

ASE Group(Taiwan)

Amkor(U.S.)

UMC(Taiwan)

Stmicroelectronics(Switzerland)

Broadcom(U.S.)

Intel(U.S.)

Jiangsu Changjiang Electronics(China)

Market segment by regions, regional analysis covers

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North America (United States, Canada, and Mexico)

Europe (Germany, France, UK, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia, Australia and Rest of Asia-Pacific)

South America (Brazil, Argentina and Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe 3D IC and 2.5D IC product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of 3D IC and 2.5D IC, with revenue, gross margin and global market share of 3D IC and 2.5D IC from 2019 to 2024.

Chapter 3, the 3D IC and 2.5D IC competitive situation, revenue and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and application, with consumption value and growth rate by Type, application, from 2019 to 2030.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2019 to 2024.and 3D IC and 2.5D IC market forecast, by regions, type and application, with consumption value, from 2025 to 2030.

Chapter 11, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of 3D IC and 2.5D IC.

Chapter 13, to describe 3D IC and 2.5D IC research findings and conclusion.

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